

RD Number: RD092

RD Title: TB67B000HG Evaluation Circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	R1	1	68kΩ 0.25W	—	—	Resistor		
2		2	Socket pin	—	—	Socket pin		
3	R1A	0	Not mount	—	—	Resistor		✓
4		2	Socket pin	—	—	Socket pin		
5	R2	1	0Ω 0.25W	—	—	Short		
6		2	Socket pin	—	—	Socket pin		
7	R3	1	0.51Ω 2W	—	—	Resistor		
8		0	Socket pin	—	—	Socket pin		✓
9	R3A	0	Not mount	—	—	Resistor		✓
10	R4	0	Not mount	—	—	Resistor		✓
11	R5	0	Not mount	—	—	Resistor		✓
12	R6	0	Not mount	—	—	Resistor		✓
13	R7	0	Not mount	—	—	Resistor		✓
14	R8	0	Not mount	—	—	Resistor		✓
15	R9	0	Not mount	—	—	Resistor		✓
16	R10	0	Not mount	—	—	Resistor		✓
17	R11	0	Not mount	—	—	Resistor		✓
18	R12	0	Not mount	—	—	Resistor		✓
19	R13	0	Not mount	—	—	Resistor		✓
20	C1	1	0.01μF 50V	—	—	Capacitor		
21		2	Socket pin	—	—	Socket pin		
22	C2	1	0.1μF 50V	—	—	Capacitor		
23	C3	1	1μF 50V	—	—	Electrolytic capacitor		
24	C4	1	0.001μF 50V	—	—	Capacitor		
25	C5	0	Not mount	—	—	Capacitor		✓
26		2	Socket pin	—	—	Socket pin		

27	C6	1	10 μ F 25V	—	—	Electrolytic capacitor		
28	C7	1	0.1 μ F 50V	—	—	Capacitor		
29	C8	1	2.2 μ F 50V	—	—	Electrolytic capacitor		
30	C9	1	2.2 μ F 50V	—	—	Electrolytic capacitor		
31	C10	1	2.2 μ F 50V	—	—	Electrolytic capacitor		
32	C11	1	0.1 μ F 50V	—	—	Capacitor		
33		2	Socket pin	—	—	Socket pin		
34	C12	1	0.1 μ F 50V	—	—	Capacitor		
35		2	Socket pin	—	—	Socket pin		
36	C13	1	0.1 μ F 50V	—	—	Capacitor		
37		2	Socket pin	—	—	Socket pin		
38	C14	0	Not mount	—	—	Capacitor		✓
39	C15	0	Not mount	—	—	Capacitor		✓
40	C16	0	Not mount	—	—	Capacitor		✓
41	C17	0	Not mount	—	—	Capacitor		✓
42	C18	0	Not mount	—	—	Capacitor		✓
43	C19	0	Not mount	—	—	Capacitor		✓
44	C20	0	Not mount	—	—	Capacitor		✓
45	C21	0	Not mount	—	—	Capacitor		✓
46	C22	0	Not mount	—	—	Capacitor		✓
47	JP1	0	Short pad (open)	—	—	Short pad		✓
48	JP2	0	Short pad (open)	—	—	Short pad		✓
49	JP3	0	Short pad (open)	—	—	Short pad		✓
50	JP4	0	Short pad (open)	—	—	Short pad		✓
51	JP5	2	Short pad (short)	—	—	Short pad		
52	JP6	2	Short pad (short)	—	—	Short pad		
53	JP7	2	Short pad (short)	—	—	Short pad		
54	JP8	0	Short pad (open)	—	—	Short pad		✓
55	JP9	0	Short pad (open)	—	—	Short pad		✓
56	JP10	0	Short pad (open)	—	—	Short pad		✓
57	JP	15	Short pad (short)	—	—	Short pad		
58	FG	1	Check terminal	—	—	Logic pin		
59	VSP	1	Check terminal	—	—	Logic pin		
60	LA	1	Check terminal	—	—	Logic pin		

61	SGND2	1	Check terminal	—	—	Logic pin		
62	HU	0	Check terminal	—	—	Logic pin		✓
63	HV	0	Check terminal	—	—	Logic pin		✓
64	HW	0	Check terminal	—	—	Logic pin		✓
65	VREFOUT2	0	Check terminal	—	—	Logic pin		✓
66	SGND3	1	Check terminal	—	—	Logic pin		
67	HUP	1	Check terminal	—	—	Logic pin		
68	HUM	1	Check terminal	—	—	Logic pin		
69	HVP	1	Check terminal	—	—	Logic pin		
70	HVM	1	Check terminal	—	—	Logic pin		
71	HWP	1	Check terminal	—	—	Logic pin		
72	HWM	1	Check terminal	—	—	Logic pin		
73	VREFOUT1	1	Check terminal	—	—	Logic pin		
74	SGND4	1	Check terminal	—	—	Logic pin		
75	IDC	1	Check terminal	—	—	Logic pin		
76	PGND1	1	Check terminal	—	—	Logic pin		
77	U	1	Check terminal	—	—	Logic pin		
78	V	1	Check terminal	—	—	Logic pin		
79	W	1	Check terminal	—	—	Logic pin		
80	VBB	1	Check terminal	—	—	Logic pin		
81	PGND2	1	Check terminal	—	—	Logic pin		
82	VCC	1	Check terminal	—	—	Logic pin		
83	SGND1	1	Check terminal	—	—	Logic pin		
84	SW_FGC	1	Toggle switch	—	—	Toggle switch		
85	SW_SS	1	Toggle switch	—	—	Toggle switch		
86	SW_CW/CCW	1	Toggle switch	—	—	Toggle switch		
87	IC1	1	TB67B000HG	TB67B000HG	TOSHIBA	Motor Driver IC	HDIP30	

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